Pb-free solder paste for 0201 small chip
FC2(Type6) FC3(Type7)

HARIMA

FC series is solder paste for very small chip such as 0201 chip.
No halogen materials are used and high reliability is ensured.

■Solder paste classification

Solder composition	SnPb	SAC305	High durable	Low melting point
Powder size	Type4 (20－38μm)	Type5 (15－25μm)	Type6 (5-15μm)	Type7 (2-11μm)
IPC-Flux type	L0	L1	M0	M1
Reflow condition	Air	Nitrogen		

■Features

- High printability and solderability for small aperture printing (0201 sized chip).
- Viscosity change during continuous printing is less, achieving a long period pf production.

■Properties（representative value)

		Property（Representative value）		Note	
Product name		PS31BR-800-FC2	PS31BR-900-FC3	－	
Alloy composition		Sn-3.0Ag-0.5Cu		－	
Powder size		5-15μm(Type6)	2-11μm(Type7)	IPC J-STD-005A	
Solidus temp.		217℃		JIS Z 3198-1	
Liquidus temp.		219℃			
Halide content		0.0%		JIS Z 3197	－
Flux content		11.5%			－
Copper corrosion		No corrosion			40℃×90% 72h
Surface insulation resistance		＞1×10^{9}Ω			85℃×85% 1,000h Apply:50V Measure : 100V
Migration		No migration			
Dryness		No tackiness（Flux residue）			－
Viscosity property	Viscosity	230Pa･s	220Pa･s	JIS Z 3284-3	
	Thixotropic index	0.51	0.53		
Slump in printing		＜0.2mm gaps			
Slump in heatin		＜0.2mm gaps ※t=0.1mm			
Tackiness		＞1.0N(0～24h)			
Flux efficacy / De-wetting		Class2 / No de−wetting		JIS Z 3284-4	
Solder Ball		Class2(0、24h)			
Shelf life		6 months		Storage(0～10℃)	

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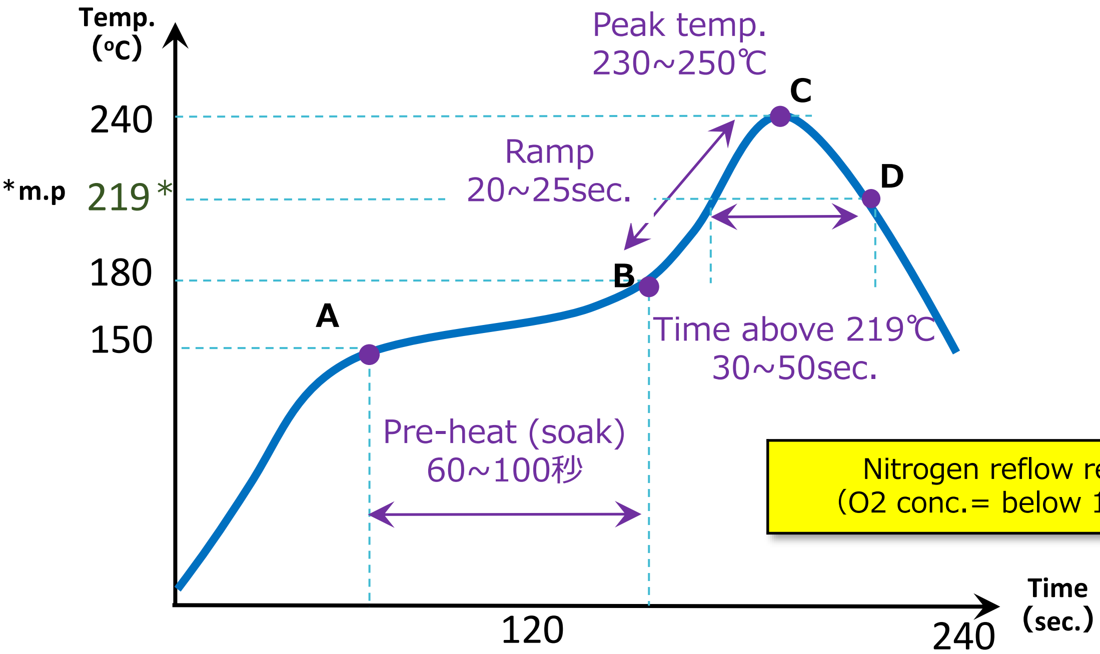
■ Recommended reflow profile



Nitrogen reflow required
(O2 conc.= below 1000ppm)

■ Precautions for handling

(1) Storage conditions

1) Store between 0 and 10℃.
2) Avoid exposing to direct sunlight.
3) Confirm the lid is closed firmly before storage.

(2) Cautions for handling

1) Avoid the handling of solder paste other than operator.
2) Wear appropriate gloves and glasses to use solder paste.
3) Wipe off solder paste with ethanol when it adheres to your skin.
4) Wash hands well after handling solder paste.
5) Set up a ventilation system at the handling place.

(3) Usage Instructions

1) Do not open the container until solder paste reaches to room temperature.
   * Solder paste quality will be deteriorated due to water condensation if you open the lid before getting to room temperature.
   *Avoid rapid heating, such as using heater.
2) Stir solder paste well before using.
3) Do not use solder paste with any other kind of solder paste or solvent.
4) Avoid using used solder paste mixed with fresh solder paste.
5) Recommended conditions for usage: temperature 22 to 28 ℃ and humidity 50% RH.